

Leadless Component Ruggedization Adhesives

Various technologies are available for ensuring critical components on printed circuit boards remain intact throughout manufacturing, assembly qualification, and service environment for the duration of product lifecycle. Should one ball-grid interconnect fail, an entire device could be compromised. DYMAX has

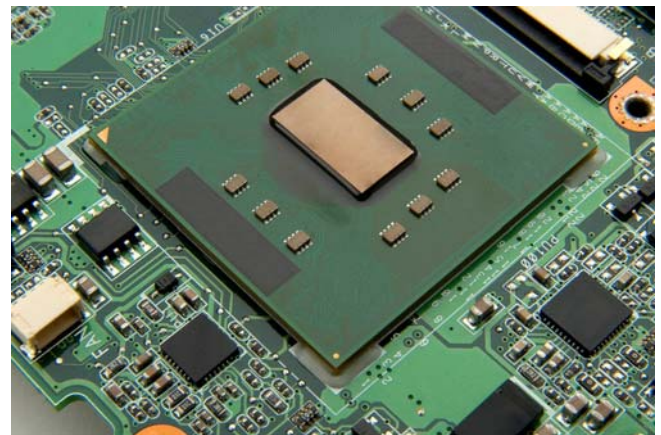
developed the next generation family of ruggedization adhesives engineered specifically for bonding high-value PCB components. DYMAX light-curable adhesives dispense and cure in seconds to provide the optimal balance of production efficiency and technical performance.

BENEFITS of LIGHT-CURABLE ADHESIVES VS UNDERFILL OR HEAT-CURE EPOXIES

- Fast dispense and cure
- Eliminate leadless component (BGA/VGA) interconnect cracking due to CTE mismatch
- Reduce stress on interconnects during push, pull, shock, drop, and vibration
- Enhance PCB life span
- Post reflow, room temperature application
- Easy rework
- Simple visual inspection

BENEFITS of DYMAX LIGHT-CURABLE LEADLESS COMPONENT REINFORCEMENT ADHESIVES

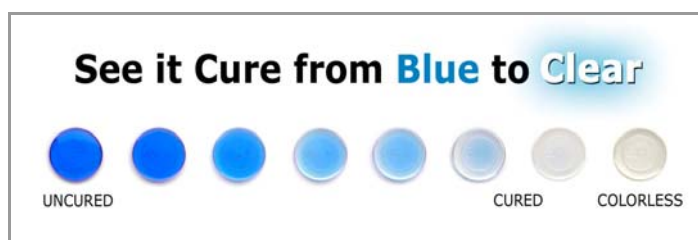
- Cure in seconds
- Engineered bead shape for wetting both board surface and component edge without seeping into shadowed area
- Highly thixotropic for **zero movement** prior to cure
- Low modulus for minimal stress in component interfaces
- Available with **See-Cure** Technology
- Exhibit improved bond strength for die and pry testing
- Halogen free
- Silicone free
- RoHS Compliant



TYPICAL APPLICATIONS

- Mobile phones, PDAs
- Laptop computers
- Gaming consoles
- GPS (global positioning systems)
- Digital music players

DYMAX SEE-CURE TECHNOLOGY*



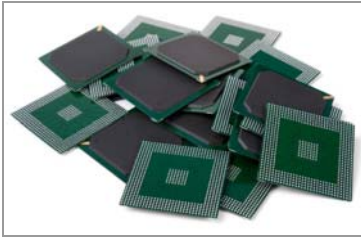
*DYMAX adhesives with See-Cure Technology have part numbers ending in "SC"

See It **Dispense**

Easily identify adhesive bead profile and coverage on substrate prior to cure

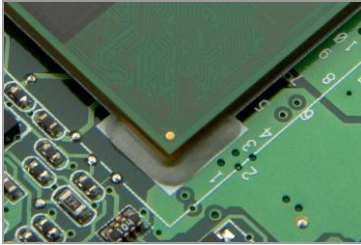
See It **Cure**

Confirm the adhesive has received enough energy to cure



ENVIRONMENTAL BENEFITS of DYMAX LIGHT-CURABLE MATERIALS:

- No VOCs
- Solvent free
- HAP free
- No energy required for curing ovens
- Documented Halogen-Free



TYPICAL COST SAVINGS of DYMAX LIGHT CURABLE MATERIALS:

- Cure in seconds; increase throughput
- Minimal floor space requirements
- Simple to dispense – no solvent management or mixing systems required
- No silicone containment required
- Eliminate labor costs associated with:
 - Complex dispensing system maintenance
 - Manual transferring of parts for long cure
- No secondary inspection of bond area

PRODUCT SPECIFICATIONS

Product Features	9422-SC	
	Typical Applications	Component ruggedization, plastics bonding
	Features	High viscosity/thixotropy for zero flow after dispense
	Viscosity	37,500 cP
	Technology	UV/Visible light cure See-Cure
	Uncured Color	Blue
	Cured Color	Clear
Product Cure Data*	9422-SC	
	Lamp Intensity	Approximate Exposure or Belt Speed
BlueWave® 200 UV Curing Spot Lamp*	5 W/cm ²	10 seconds
BlueWave® 200 UV Curing Spot Lamp*	10 W/cm ²	5 seconds
5000-EC Flood Lamp System	200 mW/cm ²	15 seconds
UVCS Conveyor with 5000-EC	200 mW/cm ²	0.9 m/min [3.0 fpm]
UVCS Conveyor with Fusion D Lamps	2700 mW/cm ²	1.5 m/min [5.0 fpm]

* Cure times based on laboratory conditions.



DYMAX Corporation - 318 Industrial Lane - Torrington, CT 06790 - Phone: 860.482.1010 - Fax: 860.496.0608 - E-mail: info@dymax.com - www.dymax.com

DYMAX Europe GmbH - Kasteler Strasse 45 - Building G 359 - 65203 Wiesbaden, Germany - Phone: +49 (0) 611.962.7900 - Fax: +49 (0) 611.962.9440 - E-mail: info_de@dymax.com - www.dymax.de

DYMAX UV Adhesives & Equipment (Shenzhen) Co., Ltd - Unit 807, Talfook Building, No. 9 Shihua Road, Futian Free Trade Zone, Shenzhen, China 518038 - Phone: +86.755.83485759 - Fax: +86.755.83485760 - E-mail: dymaxasia@dymax.com - www.dymax.com.cn

DYMAX Asia (HK) - Room 1103, 11/F., Metro Centre, Phase I, 32 Lam Hing St., Kowloon Bay, Hong Kong - Phone: +852.2460.7038 - Fax: +852.2460.7017 - E-mail: dymaxasia@dymax.com - www.dymax.com.cn

DYMAX Korea LLC - #903, CCMM B/D, 12 Yeoido-Dong, Youngdungpo-Gu, Seoul, Korea, 150-869 - Phone: 82.2.784.3434 - Fax: 82.2.784.5775 - E-mail: info@dymax.kr - www.dymax.co.kr

© 2009-2011 DYMAX Corporation. All rights reserved. All trademarks in this guide, except where noted, are the property of, or used under license by DYMAX Corporation, U.S.A.

The data contained in this bulletin is of a general nature and is based on laboratory test conditions. DYMAX does not warrant the data contained in this bulletin. Any warranty applicable to the product, its application and use is strictly limited to that contained in DYMAX's standard Conditions of Sale. DYMAX does not assume responsibility for test or performance results obtained by users. It is the user's responsibility to determine the suitability for the product application and purposes and the suitability for use in the user's intended manufacturing apparatus and methods. The user should adopt such precautions and use guidelines as may be reasonably advisable or necessary for the protection of property and persons. Nothing in this bulletin shall act as a representation that the product use or application will not infringe a patent owned by someone other than DYMAX or act as a grant of license under any DYMAX Corporation Patent. DYMAX recommends that each user adequately test its proposed use and application before actual repetitive use, using the data contained in this bulletin as a general guide. Lit244DA Rev. 5/11/2011